



## Material Content Data Sheet



<b>Sales Product Name</b>		2EDL05N06PJ		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001136744						
<b>Package</b>		PG-DSO-14-49		<b>Weight*</b>		138.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.952	0.69	0.69	6858	6858
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		103	
	non noble metal	zinc	7440-66-6	0.057	0.04		414	
	non noble metal	iron	7439-89-6	1.150	0.83		8280	
wire	non noble metal	copper	7440-50-8	46.675	33.62	34.50	336193	344990
	noble metal	gold	7440-57-5	0.229	0.16	0.16	1646	1646
encapsulation	organic material	carbon black	1333-86-4	0.175	0.13		1263	
	plastics	epoxy resin	-	9.470	6.82		68208	
	inorganic material	silicondioxide	60676-86-0	78.036	56.21	63.16	562090	631561
leadfinish	non noble metal	tin	7440-31-5	1.226	0.88	0.88	8832	8832
plating	noble metal	silver	7440-22-4	0.307	0.22	0.22	2208	2208
glue	plastics	acrylic resin	-	0.119	0.09		859	
	noble metal	silver	7440-22-4	0.423	0.30	0.39	3046	3905
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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